

March 2013

FQP6N40C / FQPF6N40C N-Channel QFET MOSFET 400 V, 6.0 A, 1.0 Ω

Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor®'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- + 6.0 A, 400 V, $R_{\rm DS(on)}$ = 1.0 Ω (Max) @V $_{\rm GS}$ = 10 V, $I_{\rm D}$ = 3.0 A
- Low Gate Charge (Typ. 16 nC)
- Low Crss (Typ. 15 pF)
- · 100% Avalanche Tested



Absolute Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter		FQP6N40C	FQPF6N40C	Unit
V _{DSS}	Drain-Source Voltage		400		V
I _D	Drain Current - Continuous (T _C = 25°C)		6	6 *	Α
	- Continuous (T _C = 100°C)		3.6	3.6 *	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	24	24 *	Α
V _{GSS}	Gate-Source Voltage		± 30		V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	270		mJ
I _{AR}	Avalanche Current	(Note 1)	6		Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	7.3		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5		V/ns
P_D	Power Dissipation (T _C = 25°C)		73	38	W
	- Derate above 25°C		0.58	0.3	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150		°C
T _L	Maximum lead temperature for soldering purposes,		300		°C
L	1/8" from case for 5 seconds				

* Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FQP6N40C	FQPF6N40C	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.71	3.31	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W

Parameter	Test Conditions	Min	Тур	Max	Unit
aracteristics					
Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$				V
Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C		0.54		V/°C
Zara Oata Valta va Basis Oamast	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ
Zero Gate Voltage Drain Current	V _{DS} = 320 V, T _C = 125°C			10	μΑ
Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V		-	-100	nA
ractoristics				I.	
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 3A		0.83	1	Ω
Forward Transconductance	$V_{DS} = 40 \text{ V}, I_{D} = 3A$ (Note 4)		4.7		S
ic Characteristics Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,		480	625	pF
Output Capacitance	f = 1.0 MHz		80	105	pF
Reverse Transfer Capacitance			15	20	pF
ng Characteristics					
Turn-On Delay Time	V 200 V I CA		13	35	ns
Turn-On Rise Time			65	140	ns
Turn-Off Delay Time	NG = 23 22		21	55	ns
Turn-Off Fall Time	(Note 4, 5)		38	85	ns
Total Gate Charge	Vps = 320 V, Ip = 6A.		16	20	nC
Gate-Source Charge	T = -		2.3		nC
Gate-Drain Charge	(Note 4, 5)		8.2		nC
Course Diede Cheresteristies er	ad Mayimum Datinga			I.	
Maximum Continuous Drain-Source Dic				6	Α
			i e		
	Forward Current			24	Α
Maximum Pulsed Drain-Source Diode F Drain-Source Diode Forward Voltage	Forward Current V _{GS} = 0 V, I _S = 6 A			24 1.4	A V
	Practeristics Drain-Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate-Body Leakage Current, Forward Gate-Body Leakage Current, Reverse Practeristics Gate Threshold Voltage Static Drain-Source On-Resistance Forward Transconductance Input Capacitance Output Capacitance Reverse Transfer Capacitance Reverse Transfer Capacitance Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Drain Charge Gate-Drain Charge	tracteristics Drain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}$, $I_D = 250 \text{ μA}$ Breakdown Voltage Temperature Coefficient $I_D = 250 \text{ μA}$, Referenced to 25°C Zero Gate Voltage Drain Current	tracteristics Drain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}$, $I_D = 250 \text{ μA}$ 400 Breakdown Voltage Temperature Coefficient $I_D = 250 \text{ μA}$, Referenced to 25°C Zero Gate Voltage Drain Current $V_{DS} = 400 \text{ V}$, $V_{GS} = 0 \text{ V}$ V _{DS} = 320 V, $V_{CS} = 125$ °C Gate-Body Leakage Current, Forward $V_{GS} = 30 \text{ V}$, $V_{DS} = 0 \text{ V}$ Gate-Body Leakage Current, Reverse $V_{GS} = -30 \text{ V}$, $V_{DS} = 0 \text{ V}$ tracteristics Gate Threshold Voltage $V_{DS} = V_{GS}$, $I_D = 250 \text{ μA}$ 2.0 Static Drain-Source On-Resistance $V_{GS} = 10 \text{ V}$, $I_D = 3A$ Forward Transconductance $V_{DS} = 40 \text{ V}$, $I_D = 3A$ (Note 4) Input Capacitance $V_{DS} = 25 \text{ V}$, $V_{GS} = 0 \text{ V}$, $I_D = 3A$ Output Capacitance $I_D = 200 \text{ V}$, $I_D = 3A$ Reverse Transfer Capacitance $I_D = 200 \text{ V}$, $I_D = 6A$,	bracteristics Drain-Source Breakdown Voltage V _{GS} = 0 V, I _D = 250 μA 400 Breakdown Voltage Temperature Coefficient I _D = 250 μA, Referenced to 25°C 0.54 Zero Gate Voltage Drain Current $V_{DS} = 400 \text{ V}$, $V_{GS} = 0 \text{ V}$ Gate-Body Leakage Current, Forward $V_{GS} = 30 \text{ V}$, $V_{DS} = 0 \text{ V}$ Gate-Body Leakage Current, Reverse $V_{GS} = 30 \text{ V}$, $V_{DS} = 0 \text{ V}$ Gate-Body Leakage Current, Reverse $V_{GS} = 30 \text{ V}$, $V_{DS} = 0 \text{ V}$ Gate-Body Leakage Current, Reverse $V_{GS} = 30 \text{ V}$, $V_{DS} = 0 \text{ V}$ Gate-Body Leakage Current, Reverse $V_{GS} = 30 \text{ V}$, $V_{DS} = 0 \text{ V}$ Gate-Body Leakage Current, Reverse $V_{GS} = 30 \text{ V}$, $V_{DS} = 0 \text{ V}$ Factoristics Gate Threshold Voltage $V_{DS} = V_{GS}$, $V_{DS} = 0 \text{ V}$ 4.7 Forward Transconductance $V_{DS} = 40 \text{ V}$, $V_{DS} = 0 \text{ V}$ 4.7 480	bracteristics Drain-Source Breakdown Voltage V _{GS} = 0 V, I _D = 250 μA 400 Breakdown Voltage Temperature Coefficient I _D = 250 μA, Referenced to 25°C 0.54 Zero Gate Voltage Drain Current $V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}$ 1 Gate-Body Leakage Current, Forward V _{GS} = 30 V, V _{DS} = 0 V 100 Gate-Body Leakage Current, Reverse $V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$ 100 racteristics Gate Threshold Voltage $V_{DS} = V_{GS}, I_{D} = 250 \mu A$ 2.0 4.0 Static Drain-Source On-Resistance $V_{CS} = 10 \text{ V}, I_{D} = 3A$ 0.83 1 Forward Transconductance $V_{DS} = 40 \text{ V}, I_{D} = 3A$ (Note 4) 4.7 Input Capacitance $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ Insurance 480 625 Output Capacitance $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ Insurance 480 625 Turn-On Delay Time $V_{DS} = 200 \text{ V}, I_{D} = 6A,$ Insurance 13

 $dI_F / dt = 100 A/\mu s$

(Note 4)

1.7

Q_{rr}

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature 2. L = 13.7 mH, $I_{AS} = 6$ A, $V_{DD} = 50$ V, $R_G = 25$ Ω , Starting $T_J = 25$ °C 3. $I_{SD} \le 6$ A, di/dt ≤ 200 A/ μ s, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25$ °C 4. Pulse Test: Pulse width ≤ 300 μ s, Duty cycle ≤ 2 % 5. Essentially independent of operating temperature

Reverse Recovery Charge

μС

Typical Characteristics

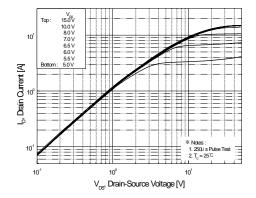


Figure 1. On-Region Characteristics

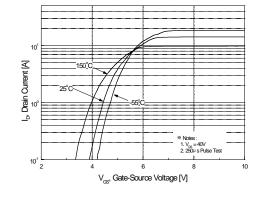


Figure 2. Transfer Characteristics

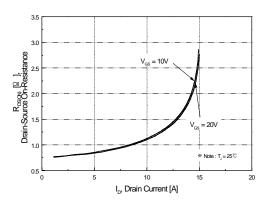


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

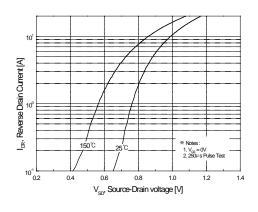


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

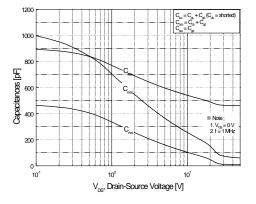


Figure 5. Capacitance Characteristics

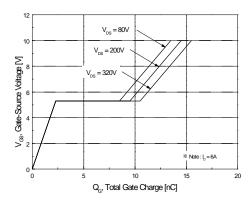


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

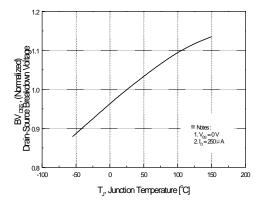
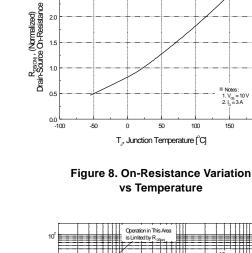


Figure 7. Breakdown Voltage Variation vs Temperature



2.0

vs Temperature

150

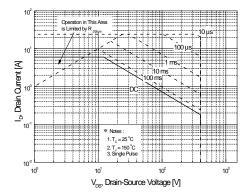


Figure 9-1. Maximum Safe Operating Area for FQP6N40C

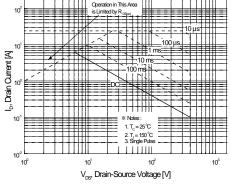


Figure 9-2. Maximum Safe Operating Area for FQPF6N40C

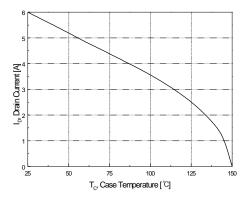


Figure 10. Maximum Drain Current vs Case Temperature

Typical Characteristics (Continued)

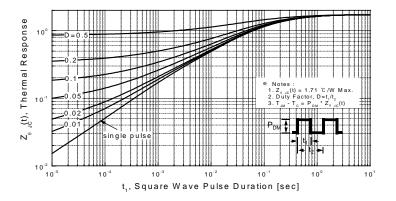


Figure 11-1. Transient Thermal Response Curve for FQP6N40C

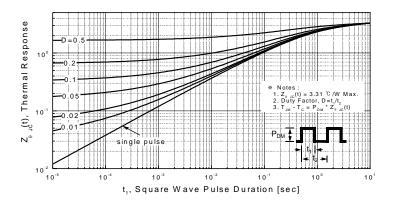
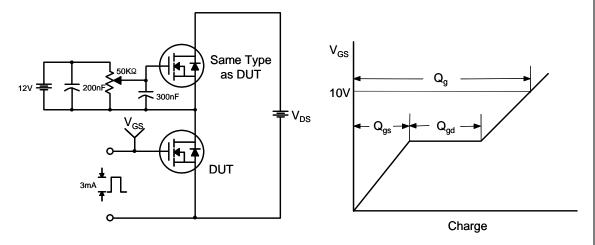
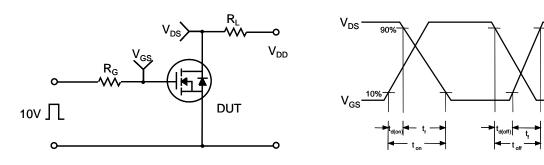


Figure 11-2. Transient Thermal Response Curve for FQPF6N40C

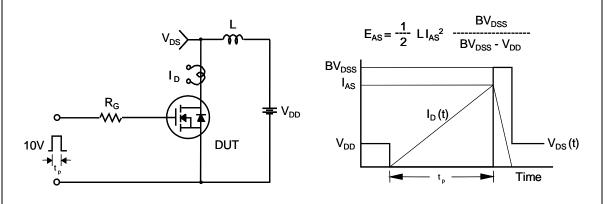
Gate Charge Test Circuit & Waveform



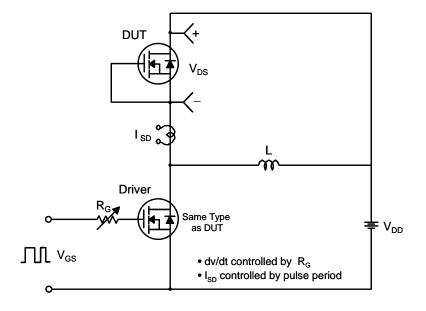
Resistive Switching Test Circuit & Waveforms

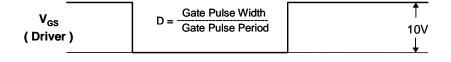


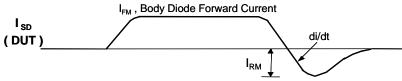
Unclamped Inductive Switching Test Circuit & Waveforms



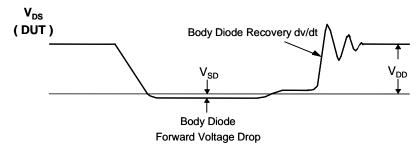
Peak Diode Recovery dv/dt Test Circuit & Waveforms

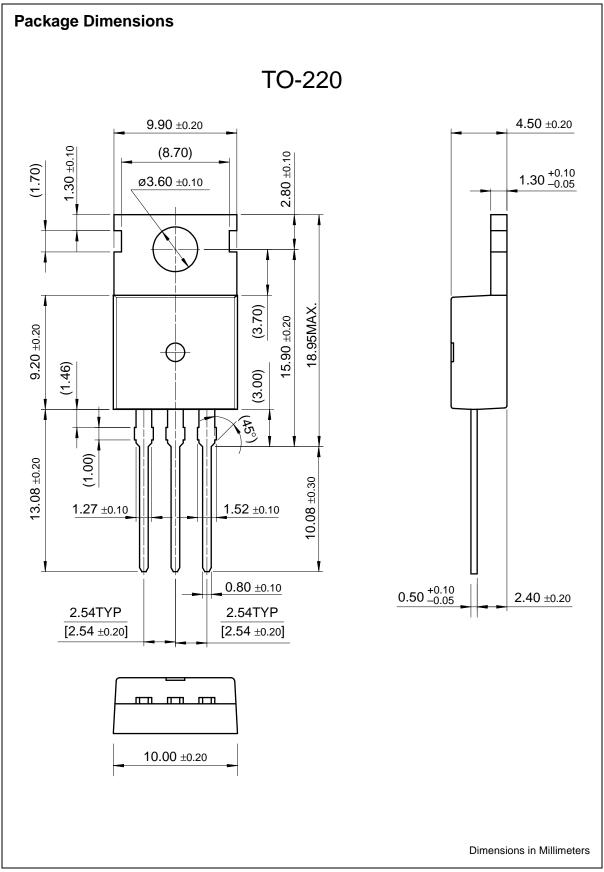


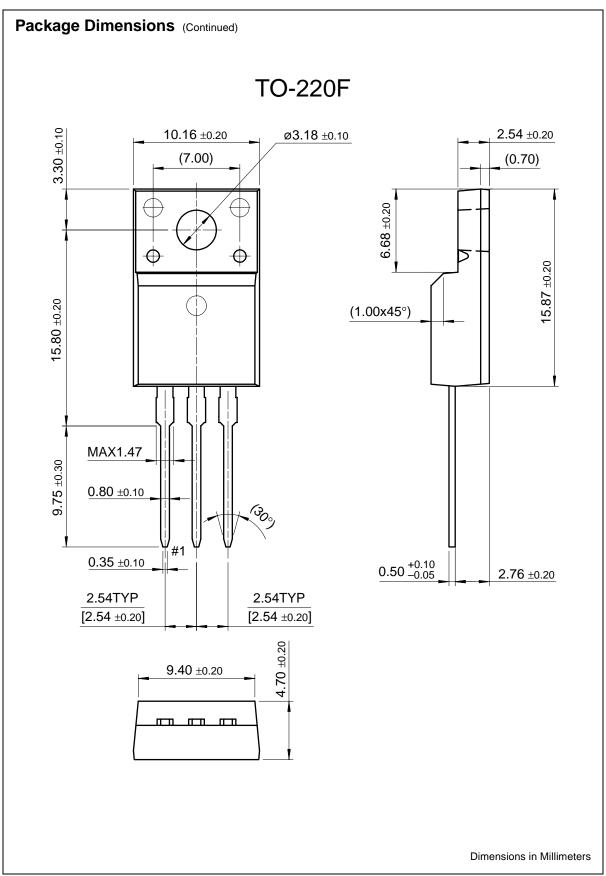




Body Diode Reverse Current











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